



REVISION RECORD			
LN	REV. NO.	APPROVED	DATE

- Notes:**
- Top & Bottom metallization Immersion Gold.
 - Metallization 0.5 oz copper.
 - Plate Vias with 1 oz copper.
 - "YELLOW" soldermask top and bottom.
 - Top & bottom silkscreen "BLACK". Bottom mirrored.
 - Do not cut copper back from edge of board.
 - Ship individual pieces.
 - Maintain .093 board thickness.
 - Warp and twist shall not exceed .007 per inch.
 - Copper overlap to board edge intentional.
 - Dielectric thickness between layers 6 and 7 may be used to adjust total board thickness to particular thickness.
 - Fill 8mil Via with non-conductive epoxy.
 - Soldermask web must be present through all QFN's .

CONFIDENTIALITY NOTICE:
 Any review, retransmission, dissemination, or use of this information by persons or entities other than the intended recipients is strictly prohibited.

12 Layers

—	.008 Rogers 4003
—	.0062 FR408
—	.008 FR408
—	.0062 FR408
—	.008 FR408
—	~.0105 FR408
—	.008 FR408
—	.0062 FR408
—	.008 FR408
—	.0062 FR408
—	.008 Rogers 4003

↑ .093 +/- .006 ↓

CENTELLAX, INC.

DESIGNER: Jason Thom	DATE: 03-24-09	TITLE: Master's Thesis Measurement Board	
CHECKED:	DATE:	CODE: A2	DRAWING NO.: P342
QUALITY CONTROL:	DATE:	SCALE:	SHEET: 1 of 1
RELEASED:	DATE:		